



Click [here](#) for the 3D model.

| Dimensions | |
|------------|------------------|
| Chip Size | 0201 |
| L | 0.6mm +/-0.03mm |
| W | 0.3mm +/-0.03mm |
| T | 0.3mm +/-0.03mm |
| B | 0.15mm +/-0.05mm |

| Packaging Specifications | |
|--------------------------|--------------------------|
| Packaging | T&R, 180mm, Plastic Tape |
| Packaging Quantity | 15000 |

| General Information | |
|---------------------|--|
| Series | CBR-SMD RF COG |
| Style | SMD Chip |
| Description | SMD, Fixed, RF, Ultra High Q, Low ESR, Class I |
| Features | Ultra High Q, Low ESR, Class I |
| RoHS | Yes |
| Termination | Tin |
| Marking | No |
| AEC-Q200 | No |
| Component Weight | 0.3 mg |
| Notes | Solder Wave or Solder Reflow. |
| Shelf Life | 78 Weeks |
| MSL | 1 |

| Specifications | |
|--|---------------------------|
| Capacitance | 3.3 pF |
| Capacitance Tolerance | +/-0.1 pF |
| Voltage DC | 100 VDC |
| Dielectric Withstanding Voltage | 250 VDC |
| Temperature Range | -55/+125°C |
| Temperature Coefficient | COG |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1MHz 1.0Vrms |
| Dissipation Factor | 0.2% 1MHz 1.0Vrms |
| Aging Rate | 0% Loss/Decade Hour |
| Insulation Resistance | 10 GOhms |
| Quality Factor | 466 |